

Microsemi Corporation

March 1, 2017

To: Digikey

Product/Process Change Notification No: 1702021

Change Classification: Major

Subject: Moving wafer fab from Bend 4" to foundry 6"

Description of Change: The chips for these products are currently built in the Bend 4" wafer fab. Over the next 24 months these chips will be transferred to a 6" foundry. The Microsemi proprietary process will be transferred to a foundry with as little change to the process flow as possible while fitting into the foundries process flow and equipment capabilities.

Reason for Change: Bend wafer fab will be closing over the next 24 months.

Application Impact:

No changes to the datasheet of these products are expected with this transfer.

Method of Identifying Changed Product:

The die PN is marked on all Microsemi PPS products affected by this change. A letter will be added to the die PN to indicate the foundry that the chip was built at. A "C" will be used to indicate Episil, an "R" will used for Ricoh and an "X" will be used for X-fab. Other foundries could be used in the future and a specific letter code will be assigned to each foundry and communicated to you as they become available.

.i.e. 106-100 = Bend fab, 106C-100 = Episil 6" foundry

Products Affected by this Change:

See Attached Pivot Table, Bend Fab Transfer tab are end customers and products affected. Customer name listed as NA indicates that Microsemi does not have the end customer name in our historical transaction

After the transfer, there will be a transition period where product from either wafer fab may be shipped while any inventory from the current Bend wafer fab is depleted.

Any orders for products required to be built in the current Bend wafer fab should be place no more than 90 days from this notice and are required to ship by Mar. 31, 2019.

Qualification Data:

Qualification data is not available at this time but will be made available as we achieve qualification at the foundries for each specific product.

Samples Availability:

Samples of the product from the 6" foundry will be made available as soon as possible with an estimated date of early 2018 for samples and gualified production units in Sept. 2018.

Please contact your local Microsemi representative to place sample orders.

Contact Information:

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Microsemi Corporation (Nasdag: MSCC) offers a comprehensive portfolio of semiconductor and system solutions for aerospace & defense, communications, data center and industrial markets. Products include high-performance and radiation-hardened analog mixed-signal integrated circuits, FPGAs, SoCs and ASICs; power management products; timing and synchronization devices and precise time solutions, setting the world's standard for time; voice processing devices; RF solutions; discrete components; enterprise storage and communication solutions; security technologies and scalable anti-tamper products; Ethernet solutions; Power-over-Ethernet ICs and midspans; as trademarks and service marks are the property of their well as custom design capabilities and services. Microsemi is headquartered in Aliso Viejo, Calif., and has approximately 4,800 employees globally. Learn more at www.microsemi.com.

MSC-F-0003 Rev 4



Any projected dates in this PCN are based on the most current product information at the time this PCN is being issued, but they may change due to unforeseen circumstances. For the latest schedule and any other information, please contact your local Microsemi Sales Office, the factory contact shown above, or your local distributor.

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Item number	Product family	Transfer
APL502B2G	MOSFET-5-LINEAR	х
APL502J	MOSFET-5-LINEAR	х
APL502LG	MOSFET-5-LINEAR	х
APL602B2G	MOSFET-5-LINEAR	х
APL602J	MOSFET-5-LINEAR	х
APL602L-1	MOSFET-5-LINEAR	х
APL602LG	MOSFET-5-LINEAR	х
APT1001R1BNG	MOSFET-4	х
APT1001RBNG	MOSFET-4	х
APT1001RBNRG	MOSFET-4-RUG	х
APT10026JN	MOSFET-4	х
APT1004RBNG	MOSFET-4	х
APT1004RKNG	MOSFET-4	х
APT10050JN	MOSFET-4	х
APT10053LNRG	MOSFET-4-RUG	х
APT20M40JN	MOSFET-4	х
APT5010JN	MOSFET-4	х
APT5012LNRG	MOSFET-4-RUG	х
APT5020BNG	MOSFET-4	х
APT5020BNRG	MOSFET-4-RUG	х
APT5025BNG	MOSFET-4	х
APT50M60JN	MOSFET-4	х
APT6015JN	MOSFET-4	х
APT8075BNG	MOSFET-4	х
ARF1500	MOSFET-5-RF	х
ARF1501	MOSFET-5-RF	х
ARF1505	MOSFET-5-RF	х
ARF1510	MOSFET-5-RF	х
ARF1511	MOSFET-5-RF	х
ARF1519	MOSFET-4-RF	х
ARF300	MOSFET-7-RF	х
ARF446G	MOSFET-5-RF	х
ARF447G	MOSFET-5-RF	х
ARF448AG	MOSFET-5-RF	х
ARF448BG	MOSFET-5-RF	х
ARF449AG	MOSFET-5-RF	х
ARF449BG	MOSFET-5-RF	х
ARF460AG	MOSFET-5-RF	х
ARF460BG	MOSFET-5-RF	х
ARF461AG	MOSFET-5-RF	х
ARF461BG	MOSFET-5-RF	х
ARF463AG	MOSFET-5-RF	х
ARF463AP1G	MOSFET-5-RF	х
ARF463BG	MOSFET-5-RF	х
ARF463BP1G	MOSFET-5-RF	х
ARF465AG	MOSFET-5-RF	х

ARF465BG	MOSFET-5-RF
ARF466AG	MOSFET-5-RF
ARF466BG	MOSFET-5-RF
ARF466FL	MOSFET-5-RF
ARF468AG	MOSFET-7-RF
ARF468BG	MOSFET-7-RF
ARF469AG	MOSFET-5-RF
ARF469BG	MOSFET-5-RF
ARF475FL	MOSFET-7-RF
ARF476FL	MOSFET-7-RF
ARF477FL	MOSFET-5-RF
ARF479	MOSFET-7-RF
VRF141	VRF-AU
VRF141G	VRF-AU
VRF141MP	VRF-AU
VRF148A	VRF-AU
VRF148AMP	VRF-AU
VRF150	VRF-AU
VRF150MP	VRF-AU
VRF151	VRF-AU
VRF151G	VRF-AU
VRF151MP	VRF-AU
VRF152	VRF-AU
VRF152G	VRF-AU
VRF152GMP	VRF-AU
VRF152MP	VRF-AU
VRF154FL	VRF-TRI
VRF154FLMP	VRF-TRI
VRF157FL	VRF-TRI
VRF157FLMP	VRF-TRI
VRF161	VRF-AU
VRF161MP	VRF-AU
VRF164FL	VRF-AU
VRF164FLMP	VRF-AU
VRF2933	VRF-AU
VRF2933FL	VRF-TRI
VRF2933FLMP	VRF-TRI
VRF2933MP	VRF-AU
VRF2944	VRF-AU
VRF2944MP	VRF-AU
VRF3933	VRF-AU
VRF3933MP	VRF-AU

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